IXYS

Product Change Notice

(PCN No.: CS04/03)

Customer:	*with a quality assurance agreement with IXYS GmbH Lampertheim*
IXYS product type:	*Package: TO-240*
Description of change:	*introduction of new paste soldering process in module assembly*
Reason for change:	*(1) improved thermal performance by better die attach quality* *(2) lead-free soldering* *(3) automation of soldering process*
Identification:	*Datecode: Suffix letter change from "D" to "P"*
Schedule of change:	*Starting March 2003 for products MCC21 und MCC56* *Plan for completion: end of October 2003*
Influence on reliability:	*improved reliability due to (1) and (3) (see reasons for change)*
Internal reference:	*TÄ017/03*

In case of any question, please contact

Initiator	Title/Function	Date	e-mail
Ostmann	*MP1 / Product marketing*	*17.03.2003*	*h.ostmann@ixys.de*

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Customer response:

(please fill in and return by e-mail, fax or mail within 4 weeks)

☐ accepted Company: _____

☐ for further questions / information Name & Position: _____

please comment Phone / Fax No.: _____

Note: **Written** response or **written** acknowledgement with statement of approval criteria, must be received within thirty (30) days of the date of this PCN or IXYS will consider this change approved.

Comments: _____

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